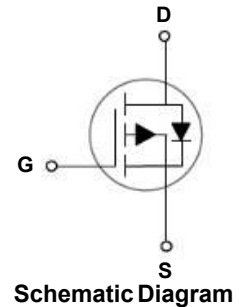
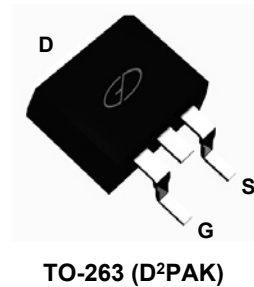


### Main Product Characteristics

$BV_{DSS}$	-60V
$R_{DS(ON)}$	4.6m $\Omega$
$I_D$	-140A



### Features and Benefits

- Advanced MOSFET process technology
- Ideal for high efficiency switched mode power supplies
- Low on-resistance with low gate charge
- Fast switching and reverse body recovery



### Description

The GSFT06131 utilizes the latest techniques to achieve high cell density and low on-resistance. These features make this device extremely efficient and reliable for use in high efficiency switch mode power supply and a wide variety of other applications.

### Absolute Maximum Ratings ( $T_C=25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Max.	Unit
Drain-Source Voltage	$V_{DS}$	-60	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Drain Current-Continuous ( $T_C=25^\circ\text{C}$ )	$I_D$	-140	A
Drain Current-Continuous ( $T_C=100^\circ\text{C}$ )		-88	
Drain Current-Pulsed <sup>1</sup>	$I_{DM}$	-560	A
Single Pulse Avalanche Energy <sup>2</sup>	$E_{AS}$	720	mJ
Single Pulse Avalanche Current <sup>2</sup>	$I_{AS}$	-120	A
Power Dissipation ( $T_C=25^\circ\text{C}$ )	$P_D$	183	W
Power Dissipation-Derate above $25^\circ\text{C}$		1.47	
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	62	$^\circ\text{C}/\text{W}$
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	0.68	$^\circ\text{C}/\text{W}$
Operating Junction Temperature Range	$T_J$	-55 To +150	$^\circ\text{C}$
Storage Temperature Range	$T_{STG}$	-55 To +150	$^\circ\text{C}$

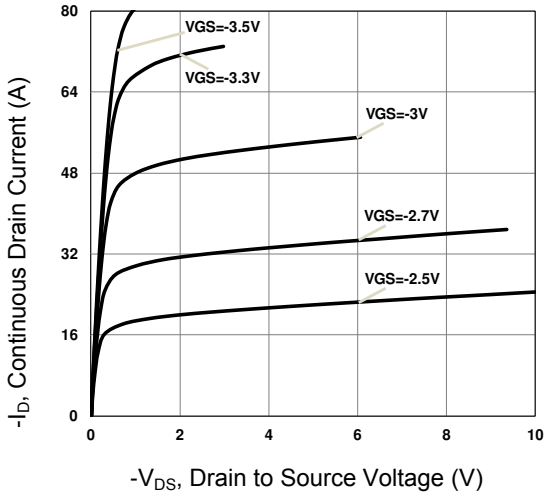
**Electrical Characteristics** ( $T_J=25^{\circ}\text{C}$  unless otherwise specified)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
<b>On / Off Characteristics</b>						
Drain-Source Breakdown Voltage	$BV_{DSS}$	$V_{GS}=0V, I_D=-250\mu A$	-60	-	-	V
$BV_{DSS}$ Temperature Coefficient	$\Delta BV_{DSS}/\Delta T_J$	Reference to $25^{\circ}\text{C}$ , $I_D=1mA$	-	0.036	-	$V/^{\circ}\text{C}$
Drain-Source Leakage Current	$I_{DSS}$	$V_{DS}=-60V, V_{GS}=0V,$ $T_J=25^{\circ}\text{C}$	-	-	-1	$\mu A$
		$V_{DS}=-48V, V_{GS}=0V,$ $T_J=125^{\circ}\text{C}$	-	-	-10	$\mu A$
Gate-Source Leakage Current	$I_{GSS}$	$V_{GS}=\pm 20V, V_{DS}=0V$	-	-	$\pm 100$	nA
Static Drain-Source On-Resistance	$R_{DS(ON)}$	$V_{GS}=-10V, I_D=-50A$	-	3.8	4.6	m $\Omega$
		$V_{GS}=-4.5V, I_D=-25A$	-	5	6	
Gate Threshold Voltage	$V_{GS(th)}$	$V_{GS}=V_{DS}, I_D=-250\mu A$	-1.2	-1.6	-2.5	V
$V_{GS(th)}$ Temperature Coefficient	$\Delta V_{GS(th)}$		-	-6.3	-	mV/ $^{\circ}\text{C}$
Forward Transconductance	$g_{fs}$	$V_{DS}=-10V, I_D=-3A$	-	18	-	S
<b>Dynamic and Switching Characteristics</b>						
Total Gate Charge <sup>3,4</sup>	$Q_g$	$V_{DS}=-48V, I_D=-5A$ $V_{GS}=-10V$	-	280	420	nC
Gate-Source Charge <sup>3,4</sup>	$Q_{gs}$		-	35	53	
Gate-Drain Charge <sup>3,4</sup>	$Q_{gd}$		-	60	90	
Turn-On Delay Time <sup>3,4</sup>	$t_{d(on)}$	$V_{DD}=-48V, R_G=6\Omega$ $V_{GS}=-10V, I_D=-1A$	-	87.5	131	nS
Rise Time <sup>3,4</sup>	$t_r$		-	256	380	
Turn-Off Delay Time <sup>3,4</sup>	$t_{d(off)}$		-	503	750	
Fall Time <sup>3,4</sup>	$t_f$		-	245	368	
Input Capacitance	$C_{iss}$	$V_{DS}=-25V, V_{GS}=0V,$ $F=1MHz$	-	16000	24000	pF
Output Capacitance	$C_{oss}$		-	920	1440	
Reverse Transfer Capacitance	$C_{rss}$		-	760	1150	
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>						
Continuous Source Current	$I_S$	$V_G=V_D=0V,$ Force Current	-	-	-140	A
Pulsed Source Current	$I_{SM}$		-	-	-280	A
Diode Forward Voltage	$V_{SD}$	$V_{GS}=0V, I_S=-1A,$ $T_J=25^{\circ}\text{C}$	-	-	1	V
Reverse Recovery Time	$t_{rr}$	$V_R=-50V, I_S=-10A,$ $di/dt=100A/\mu s,$ $T_J=25^{\circ}\text{C}$	-	75	-	nS
Reverse Recovery Charge	$Q_{rr}$		-	110	-	nC

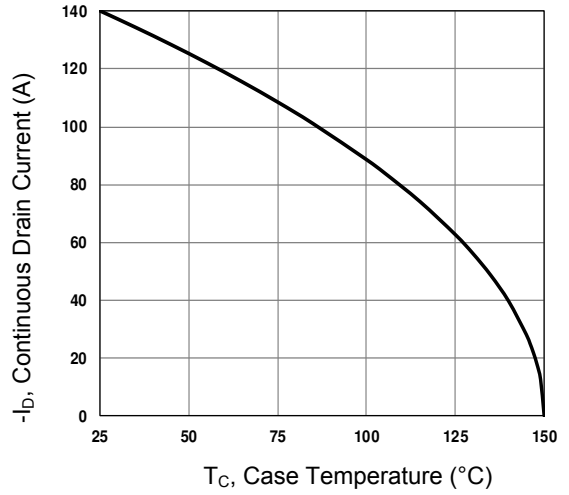
Note:

1. Repetitive rating: Pulsed width limited by maximum junction temperature.
2.  $V_{DD}=-25V, V_{GS}=-10V, L=0.1mH, I_{AS}=-120A, R_G=25\Omega,$  starting  $T_J=25^{\circ}\text{C}$ .
3. Pulse test: pulse width  $\leq 300\mu s,$  duty cycle  $\leq 2\%$ .
4. Essentially independent of operating temperature.

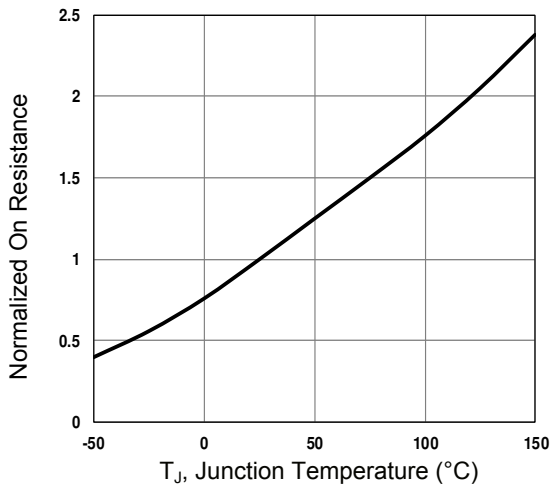
**Typical Electrical and Thermal Characteristic Curves**



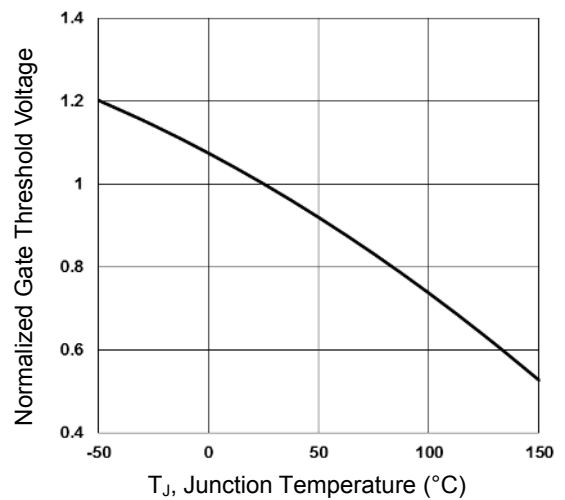
**Figure 1. Typical Output Characteristics**



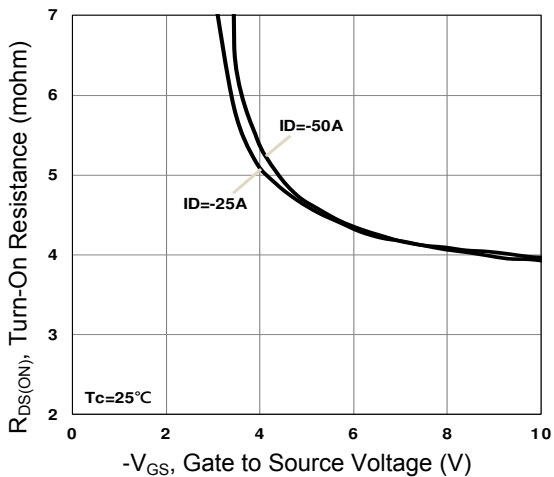
**Figure 2. Continuous Drain Current vs. T<sub>c</sub>**



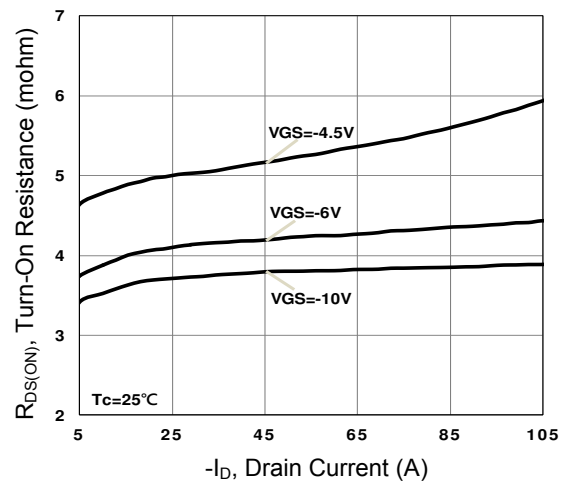
**Figure 3. Normalized R<sub>DS(on)</sub> vs. T<sub>J</sub>**



**Figure 4. Normalized V<sub>th</sub> vs. T<sub>J</sub>**

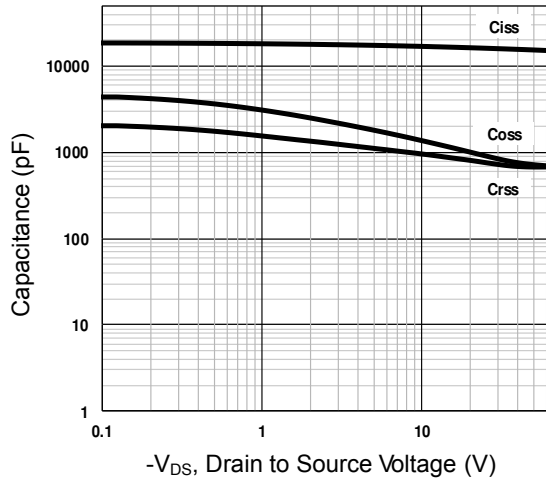


**Figure 5. Turn-On Resistance vs. V<sub>GS</sub>**

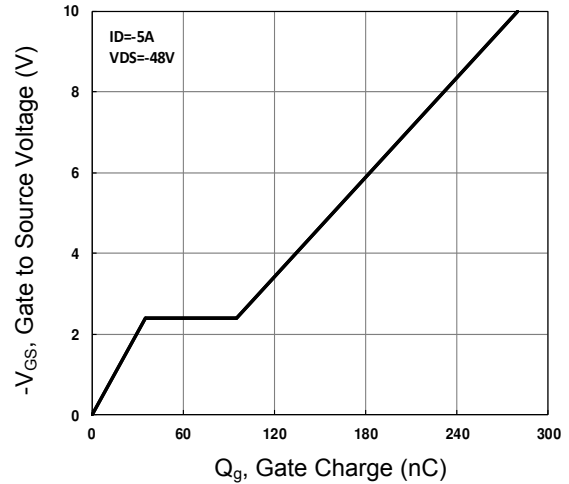


**Figure 6. Turn-On Resistance vs. I<sub>D</sub>**

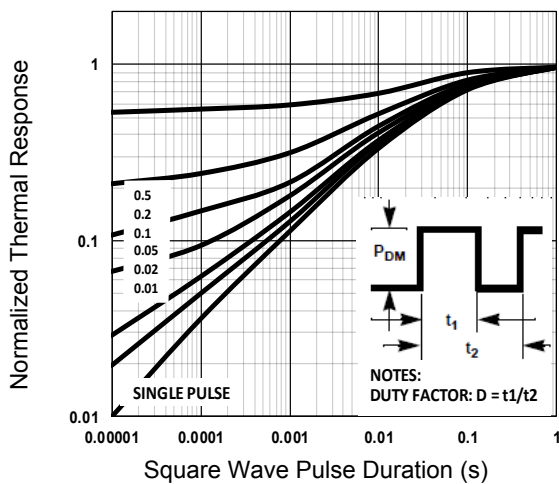
**Typical Electrical and Thermal Characteristic Curves**



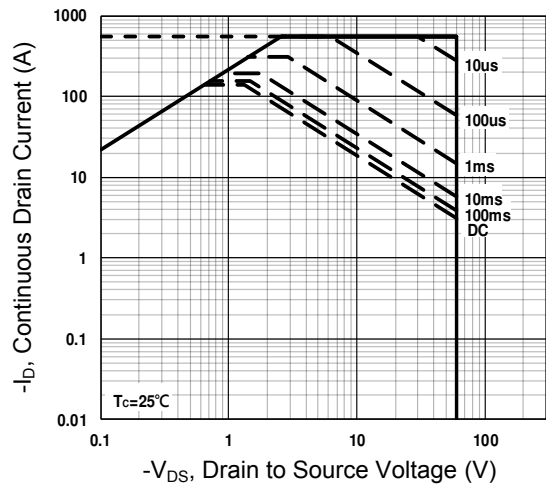
**Figure 7. Capacitance Characteristics**



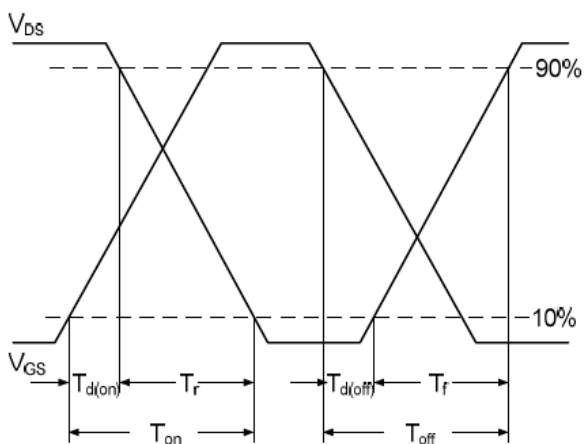
**Figure 8. Gate Charge Characteristics**



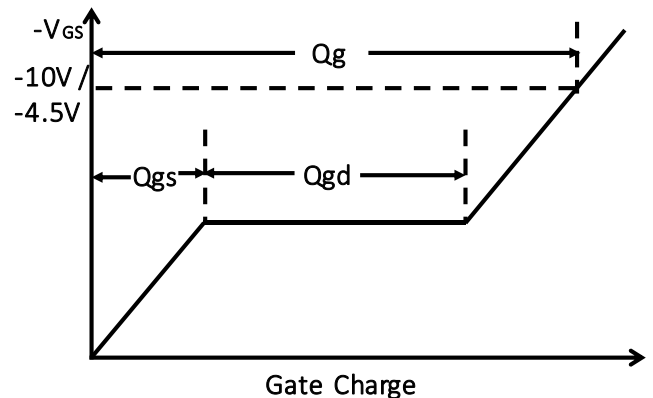
**Figure 9. Normalized Transient Impedance**



**Figure 10. Maximum Safe Operation Area**

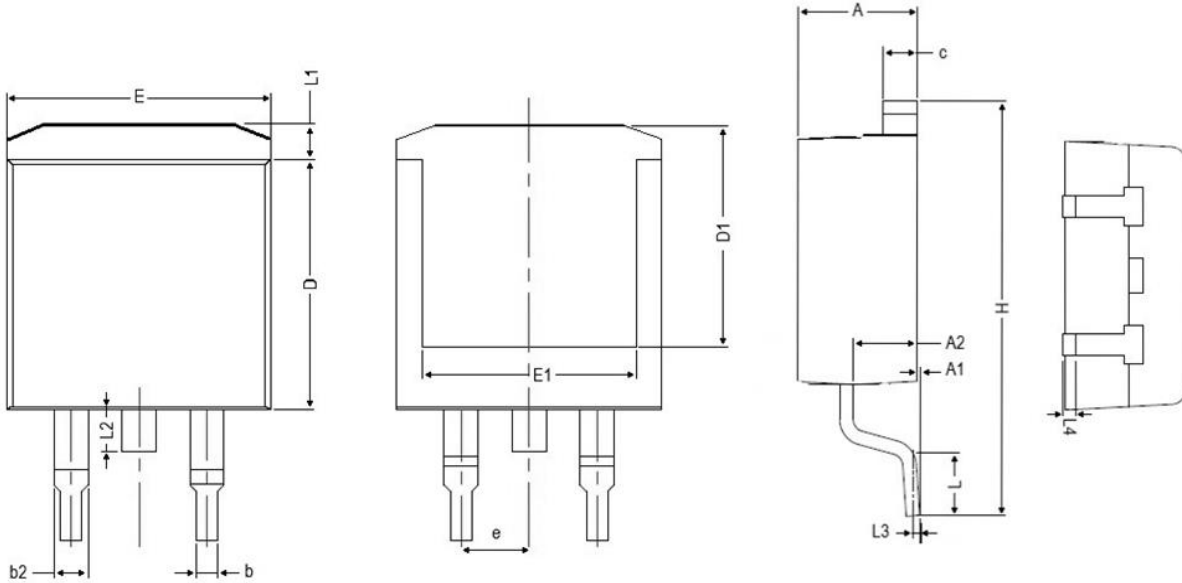


**Figure 11. Switching Time Waveform**



**Figure 12. Gate Charge Waveform**

**Package Outline Dimensions TO-263 (D<sup>2</sup>PAK)**



Symbol	Dimensions in Millimeters		Dimensions in Inches	
	Max	Min	Max	Min
A	4.850	4.200	0.191	0.165
A1	0.300	0.000	0.012	0.000
A2	2.900	2.200	0.114	0.087
b	0.950	0.700	0.037	0.028
b2	1.700	1.000	0.067	0.039
c	1.450	1.150	0.057	0.045
D	9.500	8.350	0.374	0.329
D1	9.150	6.400	0.360	0.252
E	10.500	9.600	0.413	0.378
E1	8.900	6.850	0.350	0.270
e	2.540 BSC		0.100 BSC	
H	15.900	14.600	0.626	0.575
L	2.800	1.700	0.110	0.067
L1	1.700	1.050	0.067	0.041
L2	2.100	1.300	0.083	0.051
L3	0.250 BSC		0.010 BSC	
L4	0.750	0.200	0.03	0.008